

规格书编号

SPEC NO :

# 产品规格书

# SPECIFICATION

CUSTOMER 客户: \_\_\_\_\_  
PRODUCT 产品: \_\_\_\_\_ SAW FILTER \_\_\_\_\_  
MODEL NO 型号: \_\_\_\_\_ HDF254AF11 \_\_\_\_\_  
PREPARED 编制: \_\_\_\_\_ CHECKED 审核: \_\_\_\_\_  
APPROVED 批准: \_\_\_\_\_ D A T E 日期: \_\_\_\_\_ 2006-5-11 \_\_\_\_\_

|                         |             |         |
|-------------------------|-------------|---------|
| 客户确认 CUSTOMER RECEIVED: |             |         |
| 审核 CHECKED              | 批准 APPROVED | 日期 DATE |
|                         |             |         |

无锡市好达电子有限公司  
Shoulder Electronics Limited



**1. SCOPE**

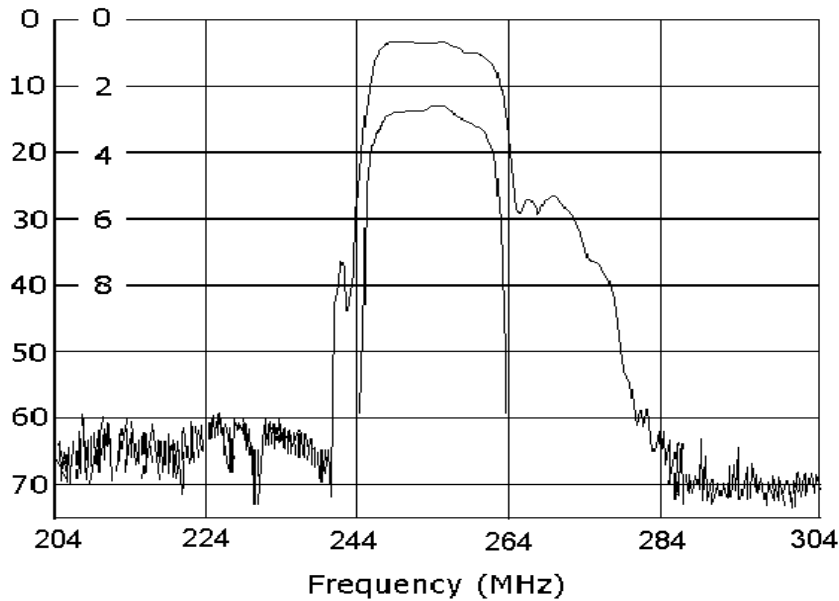
This specification shall cover the characteristics of SAW filter With F254A used for the page system.

**2. ELECTRICAL SPECIFICATION**

|                       |                |
|-----------------------|----------------|
| DC Voltage VDC        | 10V            |
| AC Voltage Vpp        | 10V50Hz/60Hz   |
| Operation temperature | -40°C to +85°C |
| Storage temperature   | -45°C to +85°C |
| RF Power Dissipation  | 0dBm           |

Electronic Characteristics

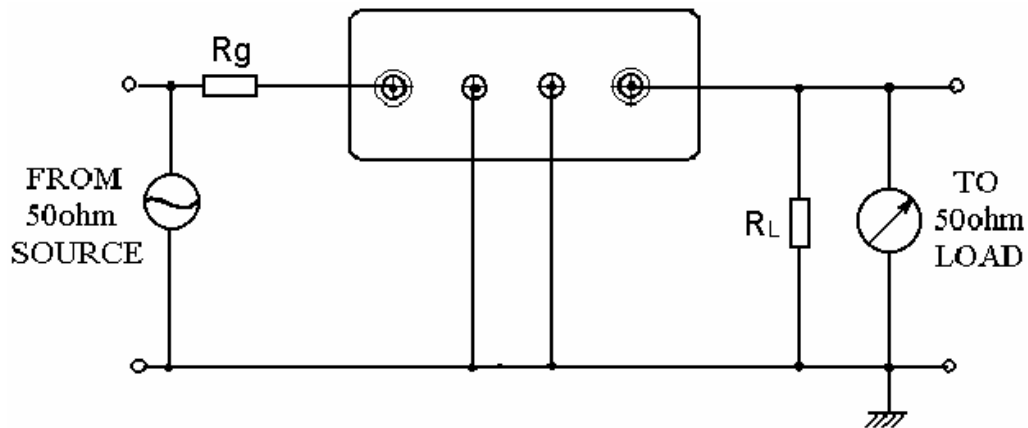
2-1.Type frequency response



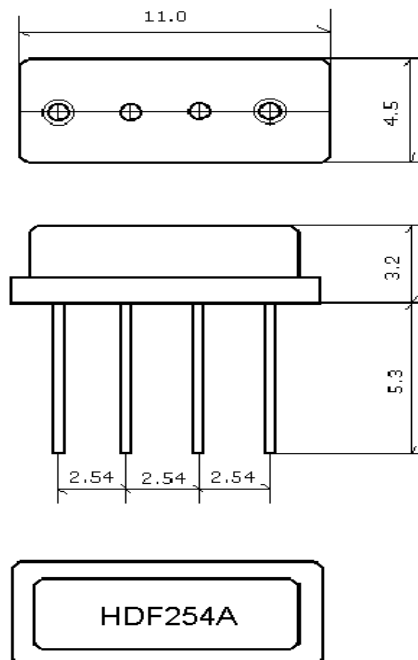
2-2Electrical characteristics

| Part number                     | F254       | Unit |
|---------------------------------|------------|------|
| Nominal center frequency (Fo)   | 254.4125   | MHz  |
| Insertion Loss                  |            |      |
| 1.253.850~254.975MHz            | ≤3.0       | dB   |
| 2.209.850~212.975MHz            | ≥55        | dB.  |
| 3.295.850~298.975MHz            | ≥50        | dB . |
| Ripple (253.850~254.975MHz)     | ≤1.5       | dB   |
| Input/Output Impedance(Nominal) | 50 Ω //0pF |      |

### 3. TEST CIRCUIT



### 4. DIMENSION



### 5. ENVIRONMENTAL CHARACTERISTICS

#### 5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

#### 5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

#### 5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high

temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

#### 5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at 260°C  $\pm$ 10°C for 10 $\pm$ 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

#### 5-5 Solderability

Subject the device terminals into the solder bath at 245°C  $\pm$ 5°C for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

#### 5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

#### 5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

## 6. REMARK

### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.